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(54) **PACKAGING METHOD TO MANUFACTURE PACKAGE FOR A HIGH-POWER LIGHT EMITTING DIODE**

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(57) **ABSTRACT**

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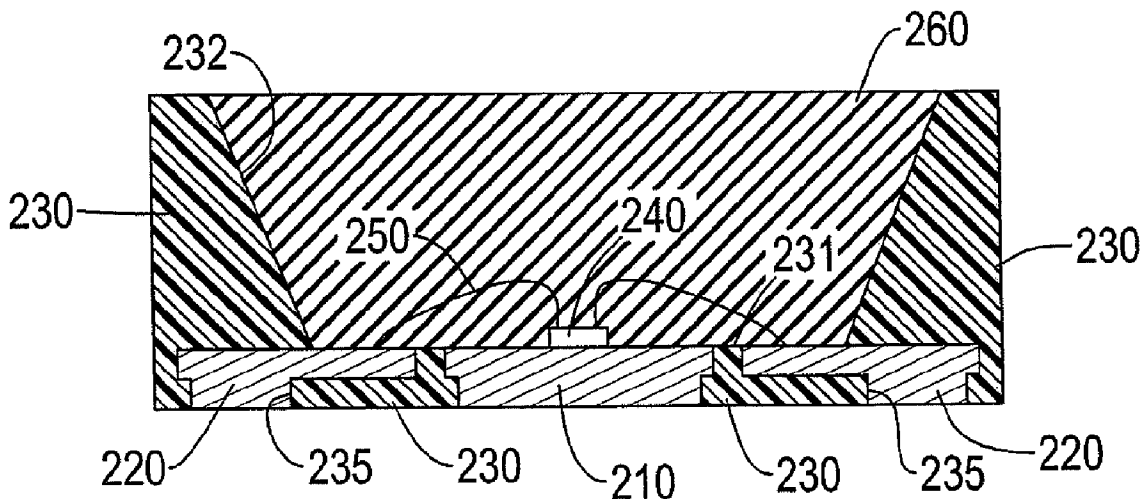
A packaging method to manufacture a package for a high-power light emitting diode (LED) has steps of (a) obtaining a metal board, (b) treating the metal board, (c) molding a cell matrix with multiple reflective bases, (d) attaching LED chips onto the dissipating boards and bonding conductive wires in each corresponding reflective base of the cell matrix, (e) encapsulating the LED chips and conductive wires in the reflective base of the cell matrix to form a after-packaging board and (f) cutting off the after-packaging board to form multiple individual high-power LED packages. Most heat from the LED chips is conducted via the dissipating board thereby improving thermal conduction efficiency and allowing more powerful and numerous LED chips to operate per package so increasing applications of LEDs. Therefore, the present invention provides different pass ways for conducting heat and electricity to improve heat conduction of the LED.

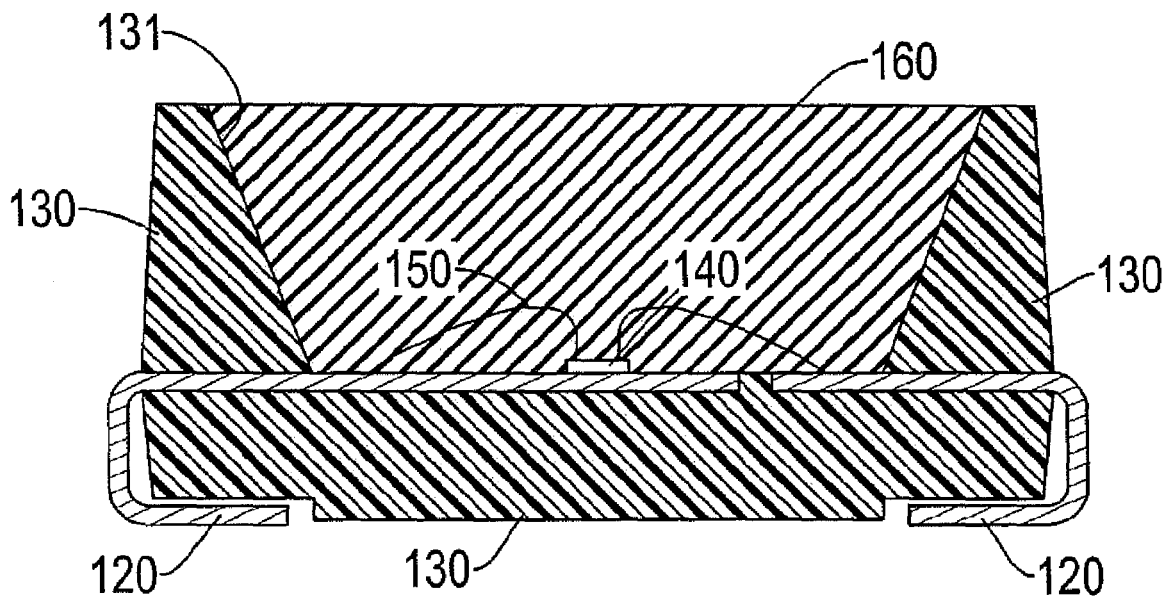
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**FIG.1**  
PRIOR ART

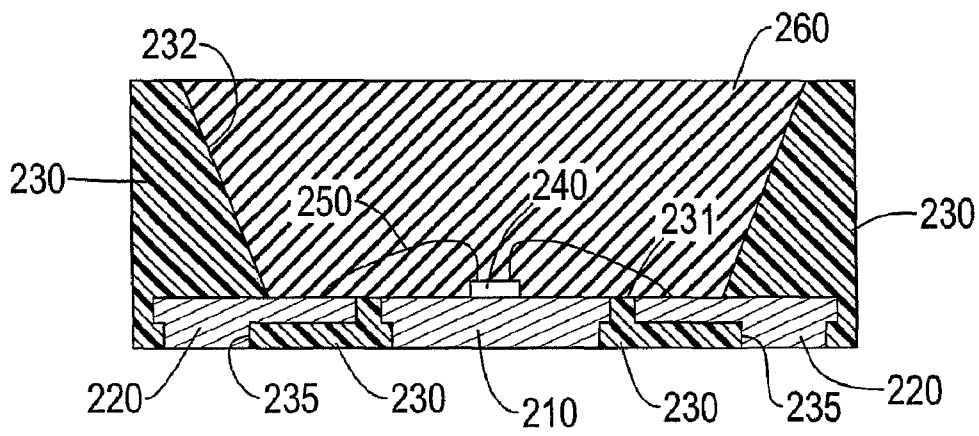


FIG.2A

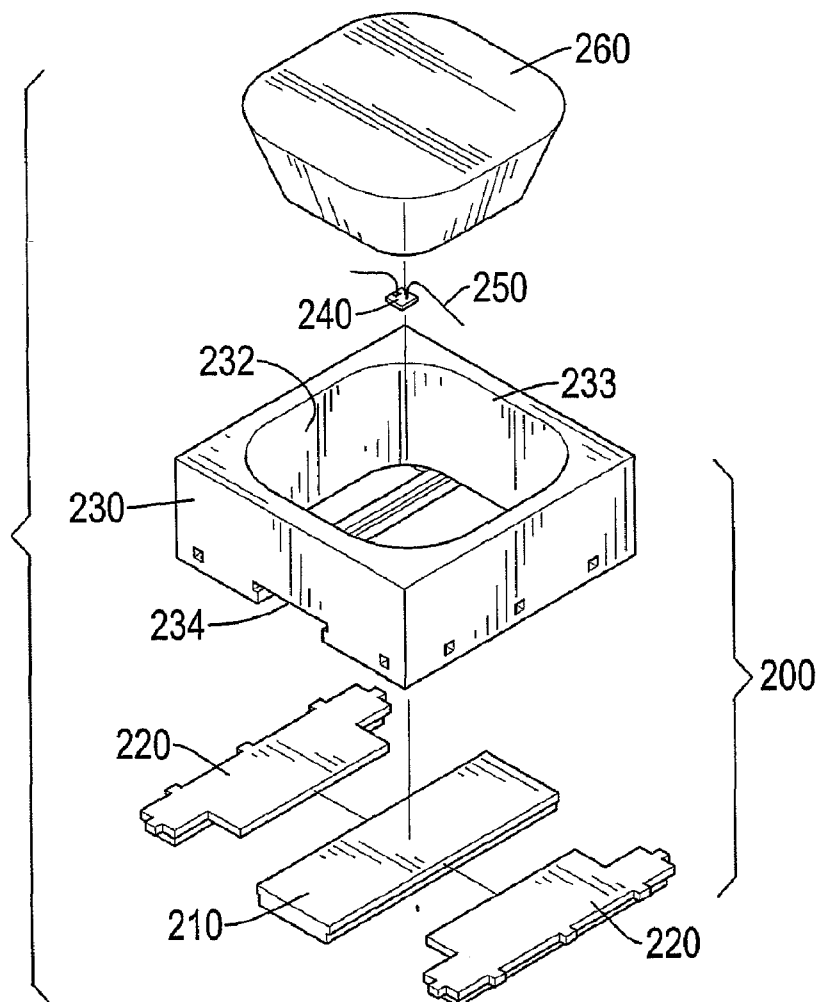


FIG.2B

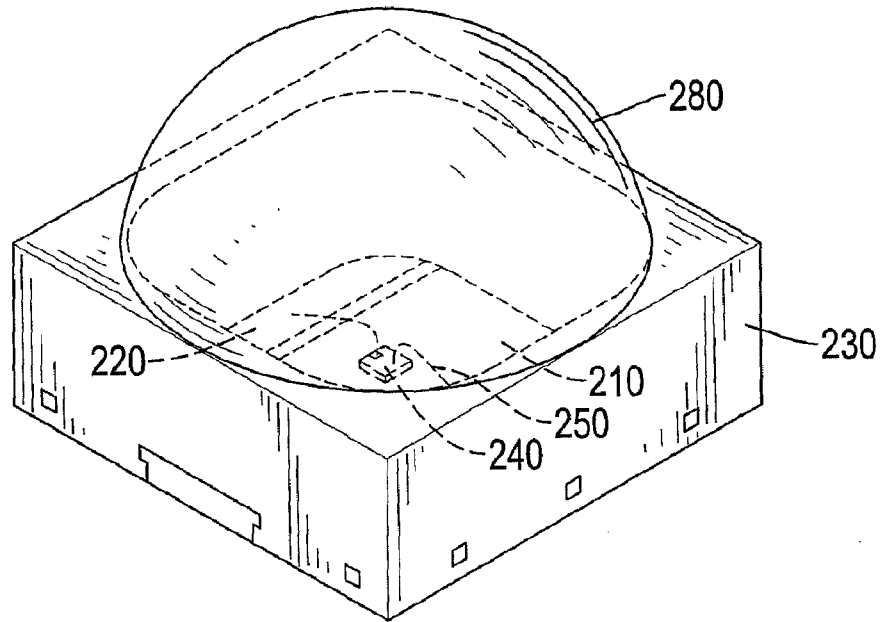


FIG. 2C

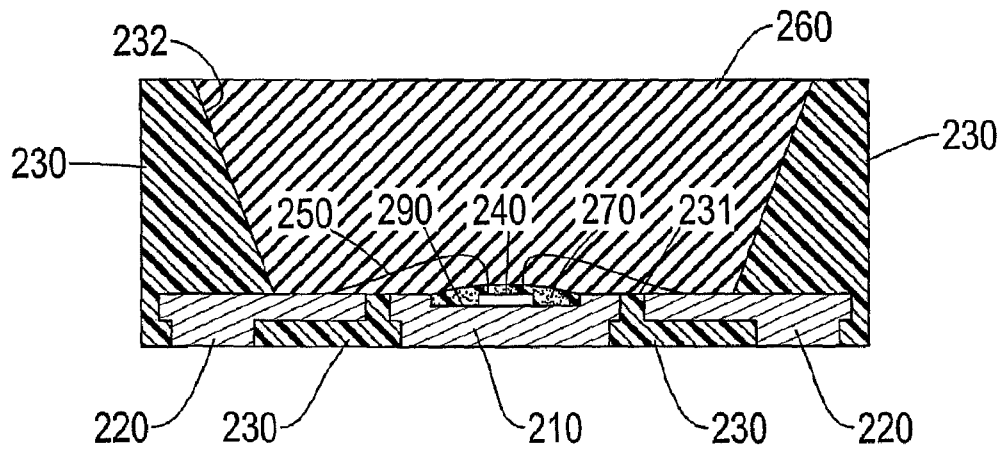


FIG. 2D

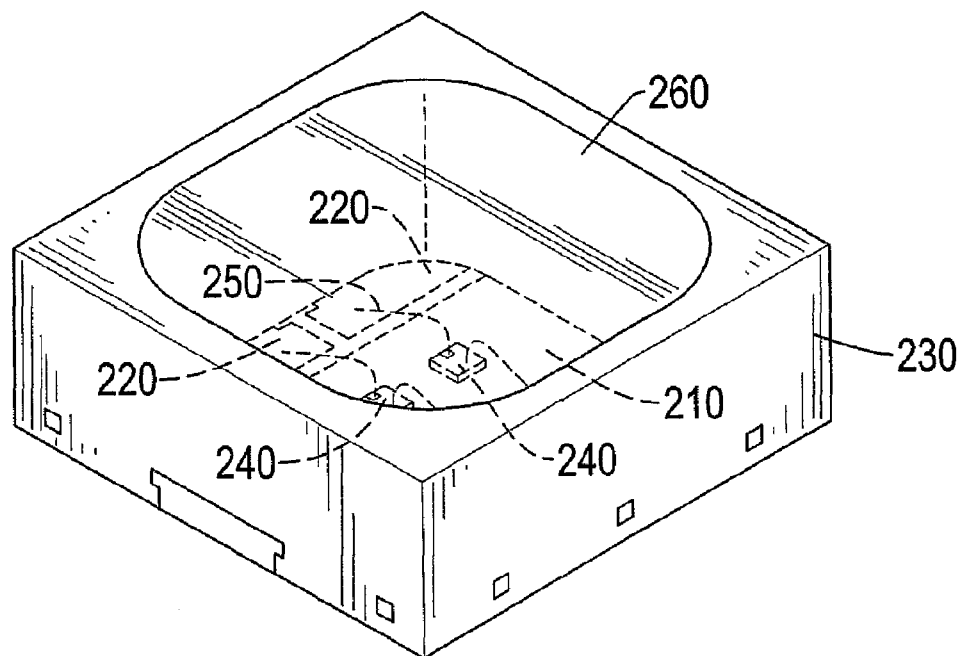


FIG. 3A

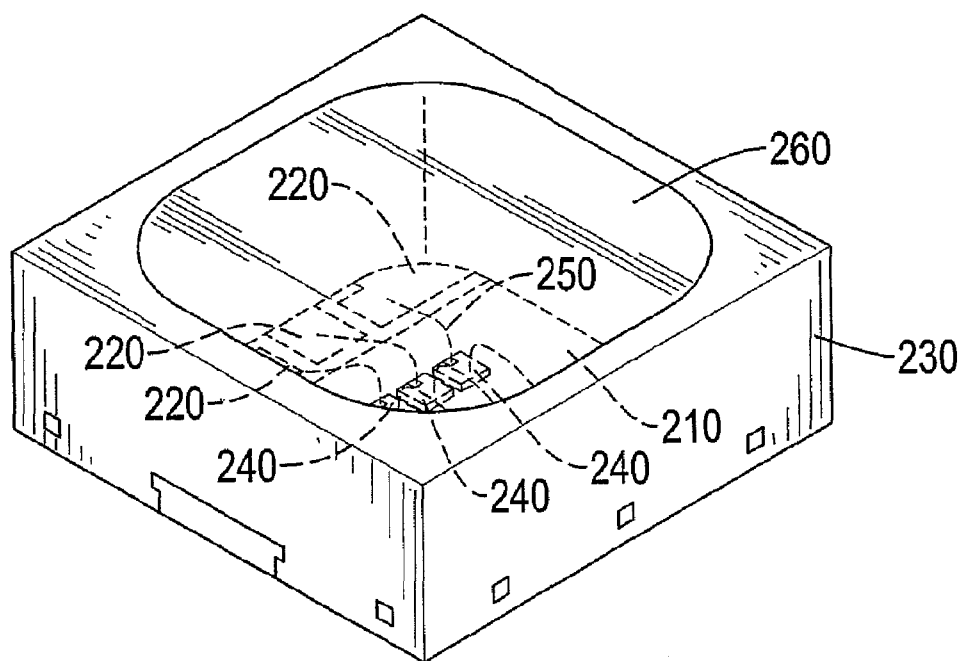


FIG. 3B

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